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May 22, 2007



To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/826,752	04/16/04
ROMEO EMMANUEL P. ALVAREZ		
"METHOD FOR FORMING A WAFER LEVEL CHIP SCALE PACKAGE, AND PACKAGE FORMED THEREBY"		
Grp. Art Unit: 2813	JAMES M. MITCHELL	

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated January 26, 2007, please consider the remarks concerning the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 29, 2007.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

5/29/07